

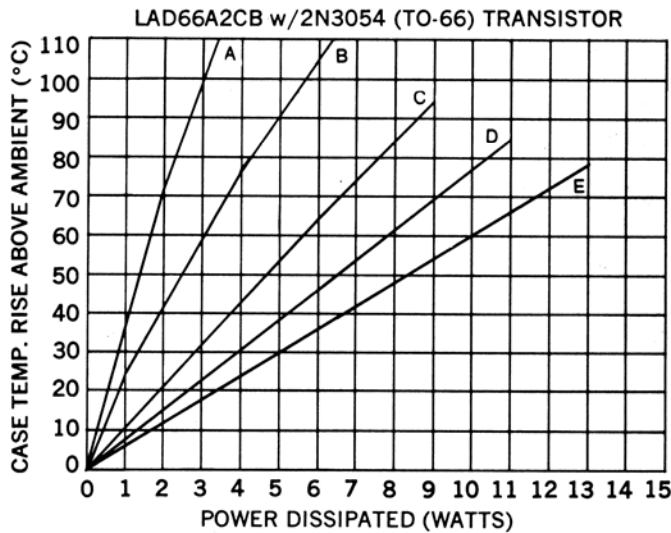
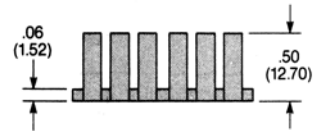
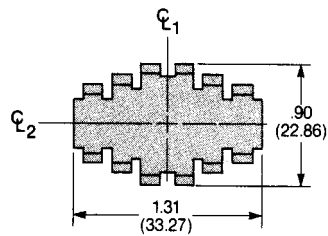
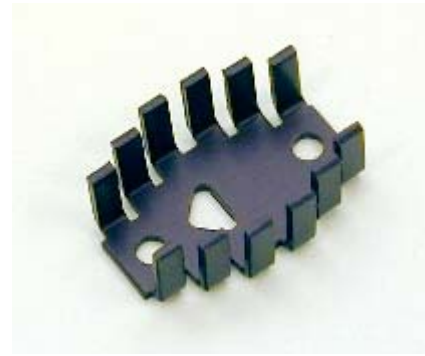
METAL CASE, CASE-MOUNTED SEMICONDUCTORS

Part Number Series LA-A2

Natural Conv. (°C/W): 19.7

Forced Air (°C/W): 6.4

Mounting Envelope: 1.31" x .90" x .25"



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 0.5-0.7 °C/W w/Joint Compound.
- Derate 0.4 °C/watt for unplated part in natural convection only.

Ordering Information

CTS IERC PART NO.			Semiconductor Accommodated	Hole patt. ref. no.	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
LA000A2U	LA000A2CB	LA000A2B	Undrilled	--	4.6
LAD66A2U	LAD66A2CB	LAD66A2B	TO-66	1 (see below)	4.6
LAIC66A2U	LAIC66A2CB	LAIC66A2B	TO-66 IC	7 (see below)	4.6

